

# 200mA, Ultra-Low Noise, Ultra-Fast CMOS LDO Regulator

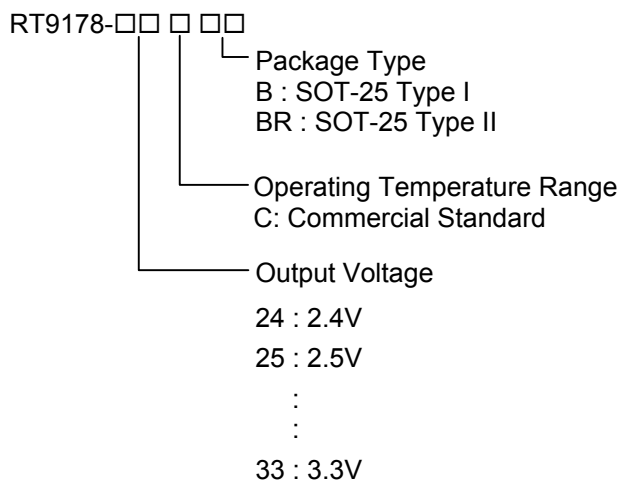
## General Description

The RT9178 is designed for portable RF and wireless applications with demanding performance and space requirements.

The RT9178's performance is optimized for battery-powered systems to deliver ultra low noise and low quiescent current. A noise bypass pin is also available for further reduction of output noise. Regulator ground current increases only slightly in dropout, further prolonging the battery life. The RT9178 also works with low-ESR ceramic capacitors, reducing the amount of board space necessary for power applications, critical in hand-held wireless devices.

The RT9178 consumes less than 0.01 $\mu$ A in shutdown mode and has fast turn-on time less than 100 $\mu$ S. The other features include ultra low dropout voltage, high output accuracy, current limiting protection, and high ripple rejection ratio. Available in the 5-lead SOT-25 package, the RT9178 also offers a range of 2.4V to 3.3V with 0.1V per step.

## Ordering Information



## Marking Information

For marking information, contact our sales representative directly or through a RichTek distributor located in your area, otherwise visit our website for detail.

## Features

- Ultra-Low-Noise for RF Application
- Ultra-Fast Response in Line/Load Transient
- Quick Start-Up (Typically 100 $\mu$ S)
- < 0.01 $\mu$ A Quiescent Current When Shutdown
- Low Dropout: 200mV at 200mA
- Wide Operating Voltage Ranges: 2.5V ~ 6.0V
- TTL-Logic-Controlled Shutdown Input
- Low Temperature Coefficient
- Current Limiting Protection
- Thermal Shutdown Protection
- Only 1 $\mu$ F Output Capacitor Required for Stability
- High Power Supply Rejection Ratio
- Custom Voltage Available

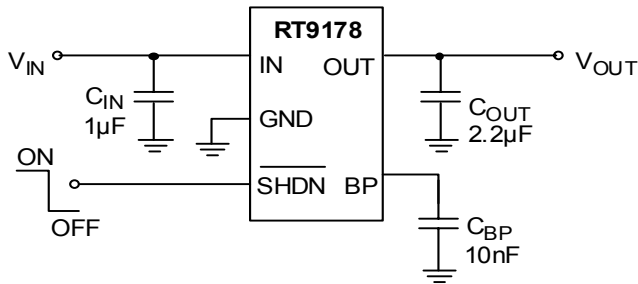
## Applications

- CDMA/GSM Cellular Handsets
- Battery-Powered Equipment
- Laptop, Palmtops, Notebook Computers
- Hand-Held Instruments
- PCMCIA Cards
- Portable Information Appliances

## Pin Configurations

Part Number	Pin Configurations
RT9178-□□CB (Plastic SOT-25)	<p>TOP VIEW</p> <p>1. VIN 2. <u>GND</u> 3. SHDN 4. BP 5. OUT</p>
RT9178-□□CBR (Plastic SOT-25)	<p>TOP VIEW</p> <p>1. OUT 2. <u>GND</u> 3. <u>VIN</u> 4. SHDN 5. BP</p>

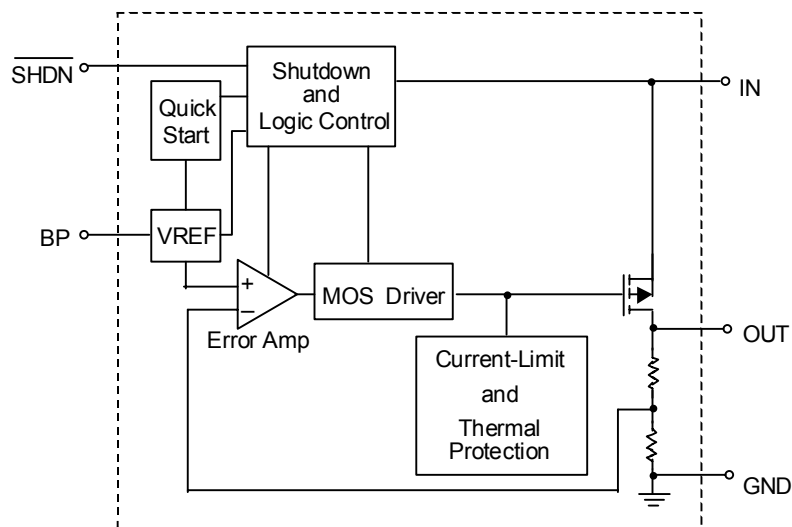
Typical Application Circuit



Pin Description

Pin No.		Pin Name	Pin Function
RT9178-□□CB	RT9178-□□CBR		
1	3	VIN	Supply Input
5	1	VOUT	Regulator Output
2	2	GND	Common Ground
3	4	$\overline{\text{SHDN}}$	Shutdown Input Logic, Active Low. If the shutdown feature is not required, connect $\overline{\text{SHDN}}$ to VIN.
4	5	BP	Reference Bypass, Connecting a 10nF capacitor to GND to reduce output noise. May be left open.

Function Block Diagram



**Absolute Maximum Ratings** (Note 1)

- Supply Input Voltage ..... 7V
- Shutdown Input Voltage ..... 7V
- Power Dissipation,  $P_D$  @  $T_A = 25^\circ\text{C}$   
   SOT-25 ..... 0.25W
- Package Thermal Resistance  
   SOT-25,  $\theta_{JA}$  ..... 250°C/W
- Lead Temperature (Soldering, 10 sec.) ..... 260°C
- Junction Temperature ..... 150°C
- Storage Temperature Range ..... -65°C to 150°C
- ESD Susceptibility (Note 2)  
   HBM ..... 2kV  
   MM ..... 200V

**Recommended Operating Conditions** (Note 3)

- Supply Input Voltage ..... 2.5V to 6V
- Shutdown Input Voltage ..... 0V to 6V
- Junction Temperature Range ..... -40°C to 125°C

**Electrical Characteristics**

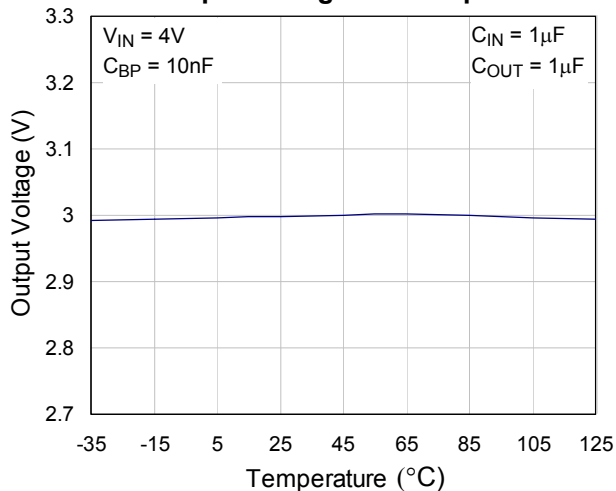
( $V_{IN} = V_{OUT} + 1V$ ,  $C_{IN} = 1\mu\text{F}$ ,  $C_{OUT} = 1\mu\text{F}$ ,  $C_{BP} = 10\text{nF}$ ,  $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units	
Output Voltage Accuracy	$\Delta V_{OUT}$	$I_{OUT} = 1\text{mA}$	-2	--	+2	%	
Current Limit	$I_{LIM}$	$R_{LOAD} = 1\Omega$	--	400	--	mA	
Quiescent Current (Note 6)	$I_Q$	$V_{SHDN} \leq 0.4V$ , $I_{OUT} = 0\text{mA}$	--	90	150	$\mu\text{A}$	
Dropout Voltage (Note 4)	$V_{DROP}$	$I_{OUT} = 200\text{mA}$	--	200	300	mV	
Line Regulation	$\Delta V_{LINE}$	$V_{IN} = (V_{OUT} + 0.3V)$ to 6.0V, $I_{OUT} = 1\text{mA}$	--	--	6	mV/V	
Load Regulation (Note 5)	$\Delta V_{LOAD}$	$1\text{mA} < I_{OUT} < 200\text{mA}$	--	--	20	mV	
Standby Current (Note 7)	$I_{STBY}$	$V_{SHDN} = \text{GND}$ , Shutdown	--	0.01	1	$\mu\text{A}$	
SHDN Input Bias Current	$I_{IBSD}$	$V_{SHDN} = \text{GND}$ or $V_{IN}$	--	0	100	nA	
SHDN Threshold	Logic-Low Voltage	$V_{IL}$	$V_{IN} = 3V$ to 5.5V, Shutdown	--	--	0.4	V
	Logic-High Voltage	$V_{IH}$	$V_{IN} = 3V$ to 5.5V, Start-Up	1.0	--	--	
Output Noise Voltage	$e_{NO}$	10Hz to 100kHz, $I_{OUT} = 200\text{mA}$ $C_{OUT} = 10\mu\text{F}$	--	50	--	$\mu\text{V}_{RMS}$	
Power Supply Rejection Rate	f = 100Hz	PSRR	$C_{OUT} = 10\mu\text{F}$ , $I_{OUT} = 200\text{mA}$	--	-70	--	dB
	f = 10kHz			--	-40	--	
Thermal Shutdown Temperature	$T_{SD}$		--	150	--	$^\circ\text{C}$	

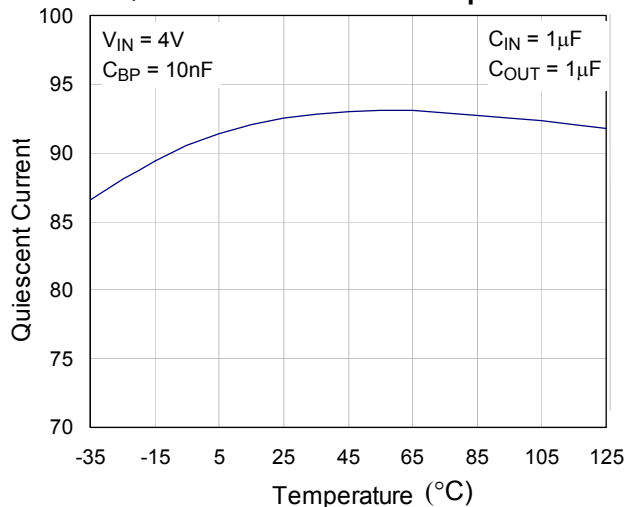
- Note 1.** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
- Note 2.** Devices are ESD sensitive. Handling precaution recommended. The human body model is a 100pF capacitor discharged through a 1.5K $\Omega$  resistor into each pin.
- Note 3.** The device is not guaranteed to function outside its operating conditions.
- Note 4.** Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value measured at 1V differential.
- Note 5.** Regulation is measured at constant junction temperature by using a 20mS current pulse. Devices are tested for load regulation in the load range from 1mA to 200mA.
- Note 6.** Quiescent, or ground current, is the difference between input and output currents. It is defined by  $I_Q = I_{IN} - I_{OUT}$  under no load condition ( $I_{OUT} = 0mA$ ). The total current drawn from the supply is the sum of the load current plus the ground pin current.
- Note 7.** Standby current is the input current drawn by a regulator when the output voltage is disabled by a shutdown signal ( $V_{SHDN} \leq 0.4V$ ). It is measured with  $V_{IN} = 6V$ .

**Typical Operating Characteristics**

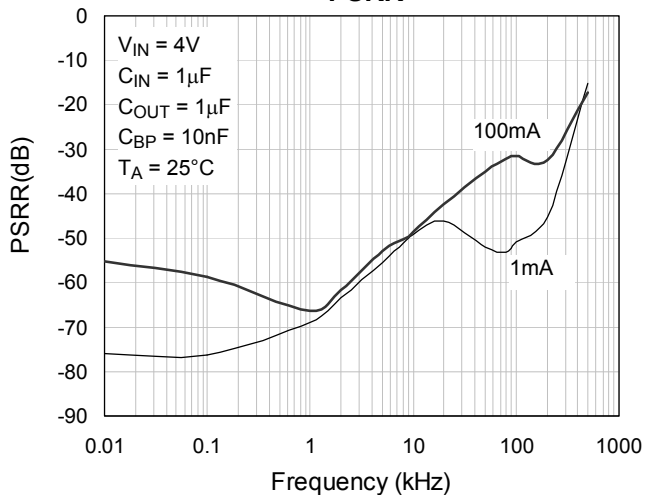
**Output Voltage vs. Temperature**



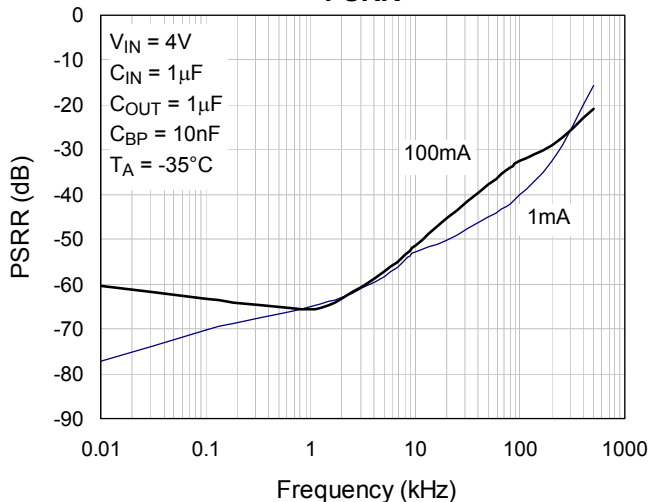
**Quiescent Current vs. Temperature**



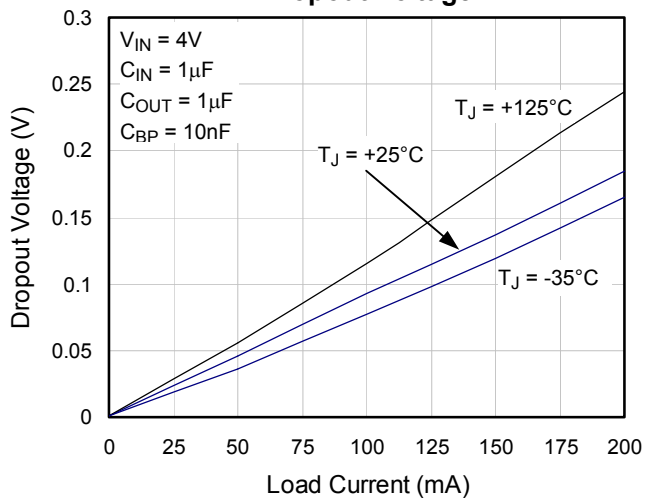
**PSRR**



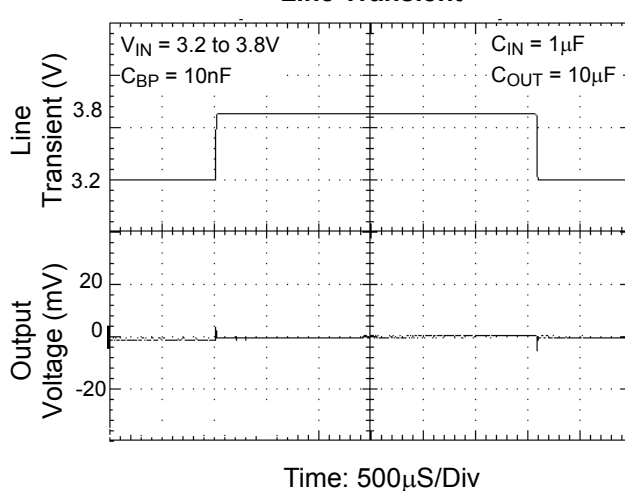
**PSRR**



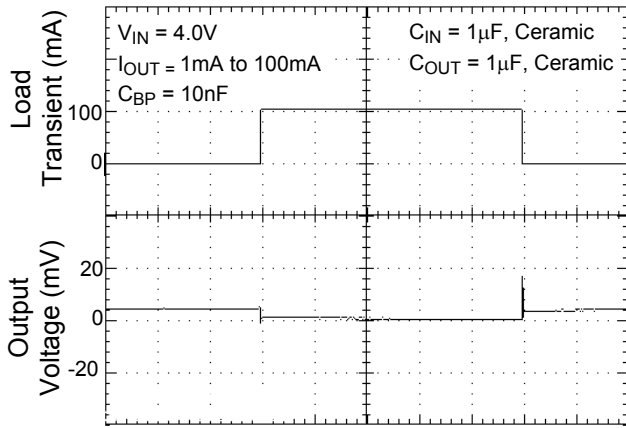
**Dropout Voltage**



**Line Transient**

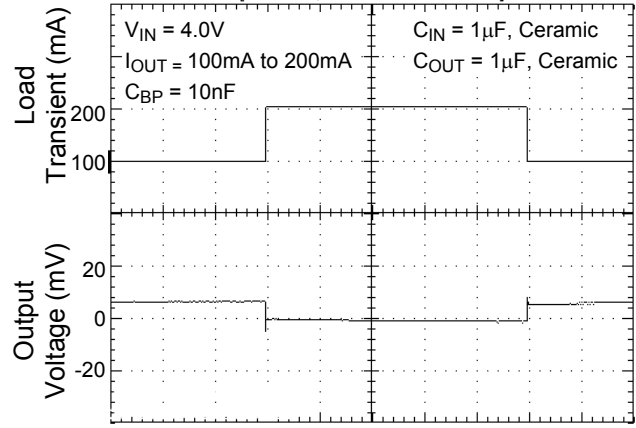


Load Transient



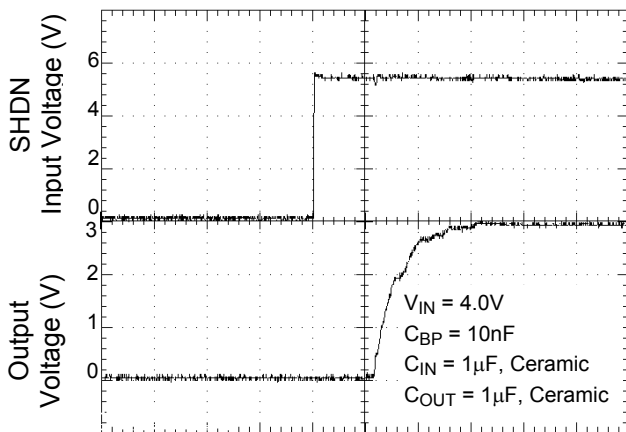
Time: 1mS/Div

Load Transient



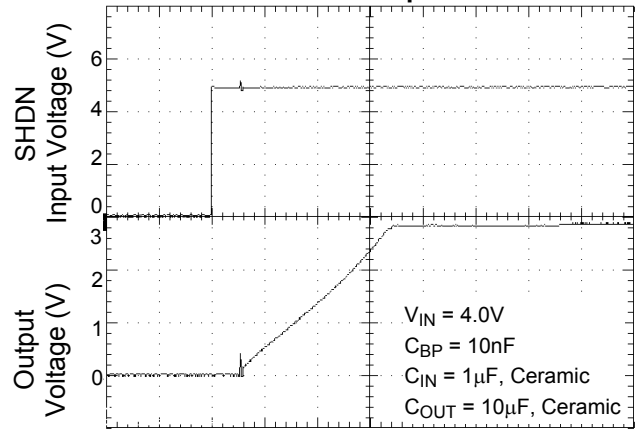
Time: 1mS/Div

Start Up



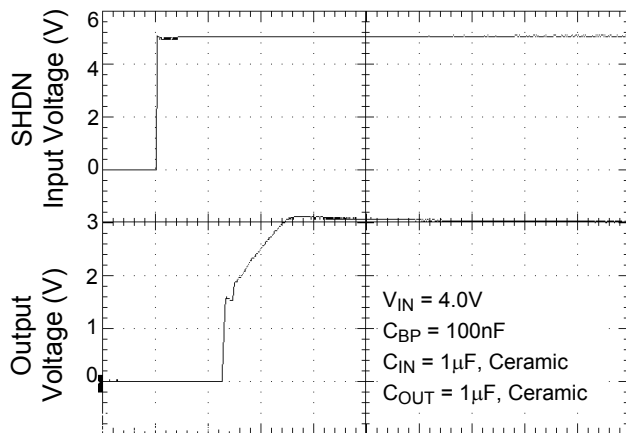
Time: 5µS/Div

Start Up



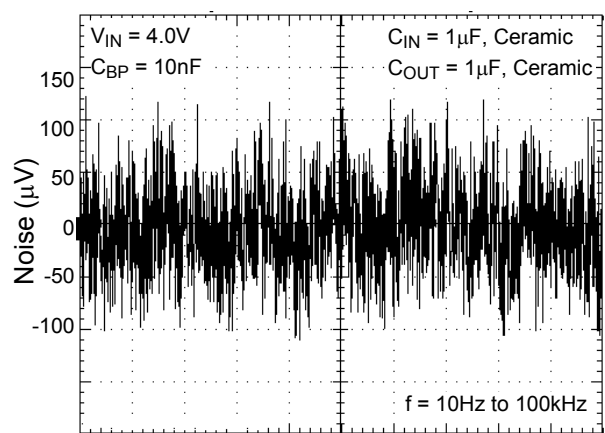
Time: 10µS/Div

Start Up



Time: 25µS/Div

Noise



Time: 10mS/Div

## Application Information

The RT9178 is ideal for mobile phone and similar battery-powered wireless applications. It provides up to 200mA, from a 2.5V to 6V input. Like any low-dropout regulator, the device requires input and output decoupling capacitors. These capacitors must be correctly selected for good performance (see Capacitor Characteristics Section). Please note that linear regulators with a low dropout voltage have high internal loop gains which require care in guarding against oscillation caused by insufficient decoupling capacitance.

### INPUT CAPACITOR

An input capacitance of  $\cong 1\mu\text{F}$  is required between the device input pin and ground directly (the amount of the capacitance may be increased without limit). The input capacitor **MUST** be located less than 1 cm from the device to assure input stability (see PCB Layout Section). A lower ESR capacitor allows the use of less capacitance, while higher ESR type (like aluminum electrolytic) require more capacitance.

Capacitor types (aluminum, ceramic and tantalum) can be mixed in parallel, but the total equivalent input capacitance/ESR must be defined as above to stable operation.

There are no requirements for the ESR on the input capacitor, but tolerance and temperature coefficient must be considered when selecting the capacitor to ensure the capacitance will be  $\cong 1\mu\text{F}$  over the entire operating temperature range.

### OUTPUT CAPACITOR

The RT9178 is designed specifically to work with very small ceramic output capacitors. The recommended minimum capacitance (temperature characteristics X7R, X5R, Z5U, or Y5V) in  $1\mu\text{F}$  to  $10\mu\text{F}$  range with  $5\text{m}\Omega$  to  $50\text{m}\Omega$  range ceramic capacitor between LDO output and GND for transient stability, but it may be increased without limit. Higher capacitance values help to improve transient.

The output capacitor's ESR is critical because it forms a zero to provide phase lead which is required for loop stability.

### REFERENCE BYPASS CAPACITOR (BP)

Connecting a 10nF between the BP (reference bypass) pin and GND significantly reduces noise on the regulator output. It should be noted that the capacitor is connected directly to a high impedance circuit in the band gap reference. Because this circuit has only a few microamperes flowing into it, any significantly loading on this node will cause a change on the regulated output voltage. For this reason, DC leakage current through the noise bypass capacitor must never exceed 100nA, and should be kept as low as possible for best output voltage accuracy. The type of capacitors best suited for the noise bypass capacitor with either NP0 or C0G dielectric typically have very low leakage. 10nF polypropylene and polycarbonate film capacitors are available in small surface mount packages and typically have extremely low leakage current.

### NO LOAD STABILITY

The device will remain stable and in regulation with no external load. This is specially important in CMOS RAM keep-alive applications.

### SHUTDOWN INPUT OPERATION

The RT9178 is shutdown by pulling the SHDN pin low, and turned on by driving the input high. If the shutdown feature is not required, the SHDN pin should be tied to VIN to keep the regulator on at all times (the SHDN pin **MUST NOT** be left floating).

To assure proper operation, the signal source used to drive the SHDN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the "Electrical Characteristics" under  $V_{IH}$  and  $V_{IL}$ . The ON/OFF signal may come from either CMOS output, or an open-collector output with pull-up resistor to the device input voltage or another logic supply. The high-level voltage may exceed the device input voltage, but must remain within the absolute maximum ratings for the SHDN pin.

### QUICK START-UP TIME

The start-up time is determined by the time constant of the bypass capacitor. The smaller the capacitor value, the shorter the power up time, but less noise gets reduced. As a result, start-up time and noise reduction need to be taken into design consideration when choosing the value of the bypass capacitor.

### INPUT-OUTPUT (DROPOUT) VOLTAGE

A regulator's minimum input-to-output voltage differential (dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the device uses a PMOS, its dropout voltage is a function of drain-to-source on-resistance,  $R_{DS(ON)}$ , multiplied by the load current:

$$V_{DROPOUT} = V_{IN} - V_{OUT} = R_{DS(ON)} \times I_{OUT}$$

### CURRENT LIMIT

The RT9178 monitors and controls the PMOS' gate voltage, limiting the output current to 400mA (typ). The output can be shorted to ground for an indefinite period of time without damaging the part.

### SHORT-CIRCUIT PROTECTION

The device is short circuit protected and in the event of a peak over-current condition, the short-circuit control loop will rapidly drive the output PMOS pass element off. Once the power pass element shuts down, the control loop will rapidly cycle the output on and off until the average power dissipation causes the thermal shutdown circuit to respond to servo the on/off cycling to a lower frequency. Please refer to the section on thermal information for power dissipation calculations.

### CAPACITOR CHARACTERISTICS

It is important to note that capacitance tolerance and variation with temperature must be taken into consideration when selecting a capacitor so that the minimum required amount of capacitance is provided over the full operating temperature range. In general, a good tantalum capacitor will show very little capacitance variation with temperature, but a ceramic may not be as good (depending on dielectric type).

Aluminum electrolytics also typically have large temperature variation of capacitance value.

Equally important to consider is a capacitor's ESR change with temperature: this is not an issue with ceramics, as their ESR is extremely low. However, it is very important in tantalum and aluminum electrolytic capacitors. Both show increasing ESR at colder temperatures, but the increase in aluminum electrolytic capacitors is so severe they may not be feasible for some applications.

#### Ceramic:

For values of capacitance in the 10 $\mu$ F to 100  $\mu$ F range, ceramics are usually larger and more costly than tantalums but give superior AC performance for by-passing high frequency noise because of very low ESR (typically less than 10m $\Omega$ ). However, some dielectric types do not have good capacitance characteristics as a function of voltage and temperature.

Z5U and Y5V dielectric ceramics have capacitance that drops severely with applied voltage. A typical Z5U or Y5V capacitor can lose 60% of its rated capacitance with half of the rated voltage applied to it. The Z5U and Y5V also exhibit a severe temperature effect, losing more than 50% of nominal capacitance at high and low limits of the temperature range.

X7R and X5R dielectric ceramic capacitors are strongly recommended if ceramics are used, as they typically maintain a capacitance range within  $\pm 20\%$  of nominal over full operating ratings of temperature and voltage. Of course, they are typically larger and more costly than Z5U/Y5U types for a given voltage and capacitance.

#### Tantalum:

Solid tantalum capacitors are recommended for use on the output because their typical ESR is very close to the ideal value required for loop compensation. They also work well as input capacitors if selected to meet the ESR requirements previously listed.



Tantalums also have good temperature stability: a good quality tantalum will typically show a capacitance value that varies less than 10~15% across the full temperature range of 125°C to -40°C. ESR will vary only about 2X going from the high to low temperature limits.

The increasing ESR at lower temperatures can cause oscillations when marginal quality capacitors are used (if the ESR of the capacitor is near the upper limit of the stability range at room temperature).

#### Aluminum:

This capacitor type offers the most capacitance for the money. The disadvantages are that they are larger in physical size, not widely available in surface mount, and have poor AC performance (especially at higher frequencies) due to higher ESR and ESL.

Compared by size, the ESR of the aluminum electrolytic is higher than either tantalum or ceramic, and it also varies greatly with temperature. A typical aluminum electrolytic can exhibit an ESR increase of as much as 50X when going from 25°C down to -40°C.

It should also be noted that many aluminum electrolytics only specify impedance at a frequency of 120Hz, which indicates they have poor high frequency performance. Only aluminum electrolytics that have an impedance specified at a higher frequency (between 20kHz and 100kHz) should be used for the device. Derating must be applied to the manufacturer's ESR specification, since it is typically only valid at room temperature.

Any applications using aluminum electrolytics should be thoroughly tested at the lowest ambient operating temperature where ESR is the maximum.

#### THERMAL CONSIDERATIONS

The RT9178 series can deliver a current of up to 200mA over the full operating junction temperature range. However, the maximum output current must be derated at higher ambient temperature to ensure the junction temperature does not exceed 125°C.

With all possible conditions, the junction temperature must be within the range specified under operating conditions. Power dissipation can be calculated based on the output current and the voltage drop across regulator.

$$P_D = (V_{IN} - V_{OUT}) I_{OUT} + V_{IN} I_{GND}$$

The final operating junction temperature for any set of conditions can be estimated by the following thermal equation:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

Where  $T_{J(MAX)}$  is the maximum junction temperature of the die (125°C) and  $T_A$  is the maximum ambient temperature. The junction to ambient thermal resistance ( $\theta_{JA}$ ) for SOT-25 package at recommended minimum footprint is 250°C/W ( $\theta_{JA}$  is layout dependent). Visit our website in which "Recommended Footprints for Soldering Surface Mount Packages" for detail.

#### PCB LAYOUT

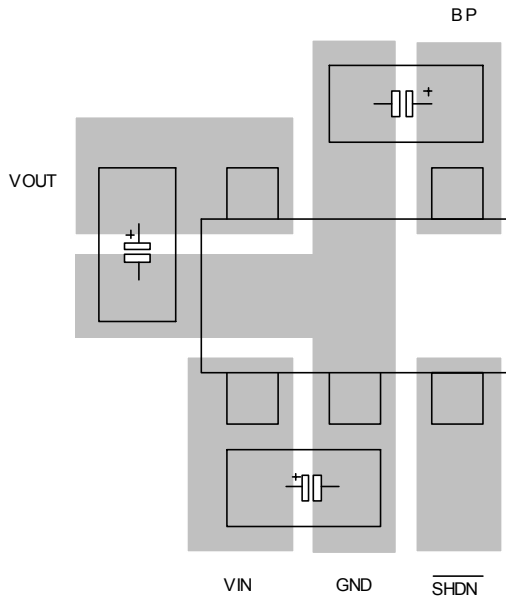
Good board layout practices must be used or instability can be induced because of ground loops and voltage drops. The input and output capacitors **MUST** be directly connected to the input, output, and ground pins of the device using traces which have no other currents flowing through them.

The best way to do this is to layout  $C_{IN}$  and  $C_{OUT}$  near the device with short traces to the  $V_{IN}$ ,  $V_{OUT}$ , and ground pins. The regulator ground pin should be connected to the external circuit ground so that the regulator and its capacitors have a "single point ground".

It should be noted that stability problems have been seen in applications where "vias" to an internal ground plane were used at the ground points of the device and the input and output capacitors. This was caused by varying ground potentials at these nodes resulting from current flowing through the ground plane. Using a single point ground technique for the regulator and its capacitors fixed the problem. Since high current flows through the traces going into  $V_{IN}$

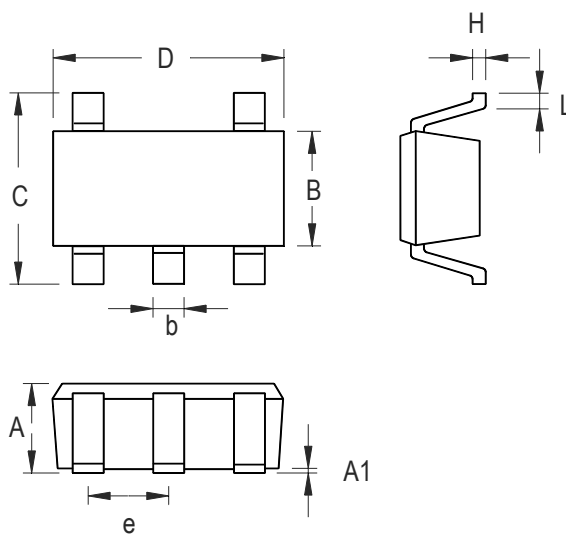
and coming from  $V_{OUT}$ , Kelvin connect the capacitor leads to these pins so there is no voltage drop in series with the input and output capacitors.

Optimum performance can only be achieved when the device is mounted on a PC board according to the diagram below:



SOT-25 (Type I) Board Layout

**Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.889	1.295	0.035	0.051
A1	0.000	0.152	0.000	0.006
B	1.397	1.803	0.055	0.071
b	0.356	0.559	0.014	0.022
C	2.591	2.997	0.102	0.118
D	2.692	3.099	0.106	0.122
e	0.838	1.041	0.033	0.041
H	0.102	0.254	0.004	0.010
L	0.356	0.610	0.014	0.024

**SOT- 25 Surface Mount Package**

**RICHTEK TECHNOLOGY CORP.**

Headquarter

5F, No. 20, Taiyuen Street, Chupei City

Hsinchu, Taiwan, R.O.C.

Tel: (8863)5526789 Fax: (8863)5526611

**RICHTEK TECHNOLOGY CORP.**

Taipei Office (Marketing)

8F-1, No. 137, Lane 235, Paochiao Road, Hsintien City

Taipei County, Taiwan, R.O.C.

Tel: (8862)89191466 Fax: (8862)89191465

Email: [marketing@richtek.com](mailto:marketing@richtek.com)